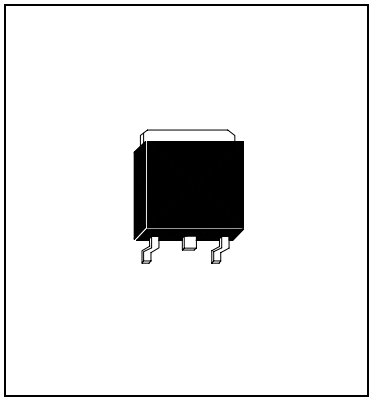
HJ45H11

PNP EPITAXIAL PLANAR TRANSISTOR



Description

The HJ45H11 is designed for various specific and general purpose applications, such as: output and driver stages of amplifiers operating at frequencies from DC to greater than 1MHz;series, shunt and switching regulators; low and high frequency inverters/converters; and many others.

Absolute Maximum Ratings (Ta=25°C)

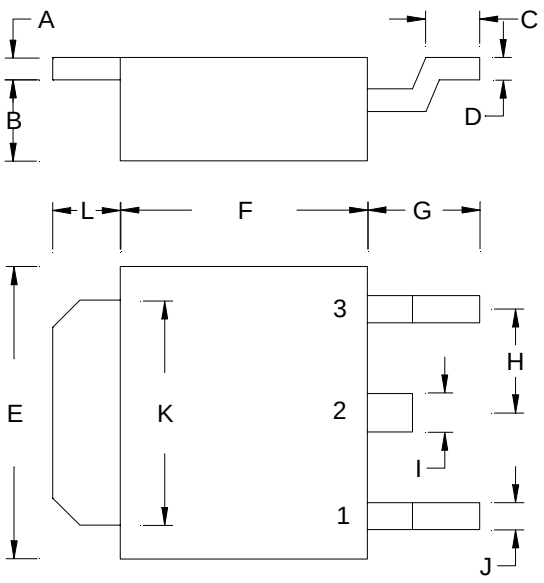
- Maximum Temperatures
  Storage Temperature ..... -55 ~ +150 °C
  Junction Temperature ..... +150 °C
- Maximum Power Dissipation
  Total Power Dissipation (Tc=25°C) ..... 20 W
- Maximum Voltages and Currents
  BVCEO Collector to Base Voltage ..... -80 V
  BVCES Collector to Emitter Voltage ..... -80 V
  BVEBO Emitter to Base Voltage ..... -5 V
  IC Collector Current ..... -10 A
  IB Base Current ..... -5 A

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCEO	-80	-	-	V	IC=-30mA, IB=0
BVCES	-80	-	-	V	IC=-1mA, IB=0
BVEBO	-5	-	-	V	IE=-1mA, IC=0
ICBO	-	-	-10	uA	VCB=-80V, IE=0
IEBO	-	-	-50	uA	VEB=-5V, IC=0
*VCE(sat)	-	-	-1	V	IC=-8A, IB=-0.8A
*VBE(sat)	-	-	-1.5	V	IC=-8A, IB=-0.8A
*hFE1	60	-	-		VCE=-1V, IC=-2A
*hFE2	40	-	-		VCE=-1V, IC=-4A
Cob	-	230	-	pF	VCB=-10V,
fT	-	40	-	MHz	VCE=-10V, IC=-500mA, f=20MHz

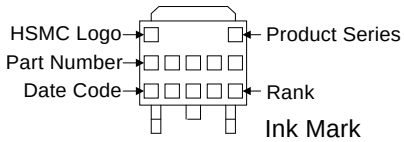
*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

TO-252 Dimension



3-Lead TO-252 Plastic Surface Mount Package
HSMC Package Code : J

Marking :



Style : Pin 1.Base 2.Collector 3.Emitter

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.0866	0.1102	2.20	2.80
B	0.0650	0.0768	1.65	1.95	H	-	*0.0906	-	*2.30
C	0.0354	0.0591	0.90	1.50	I	-	0.0354	-	0.90
D	0.0177	0.0236	0.45	0.60	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2125	0.2283	5.40	5.80	L	0.0551	0.0630	1.40	1.60

Notes : 1.Dimension and tolerance based on our Spec. dated May. 05,1996.
2.Controlling dimension : millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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